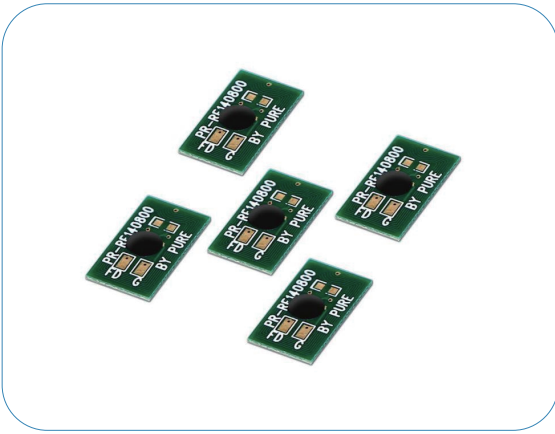


## PCB NTAG 213 NFC Tag-spec sheet



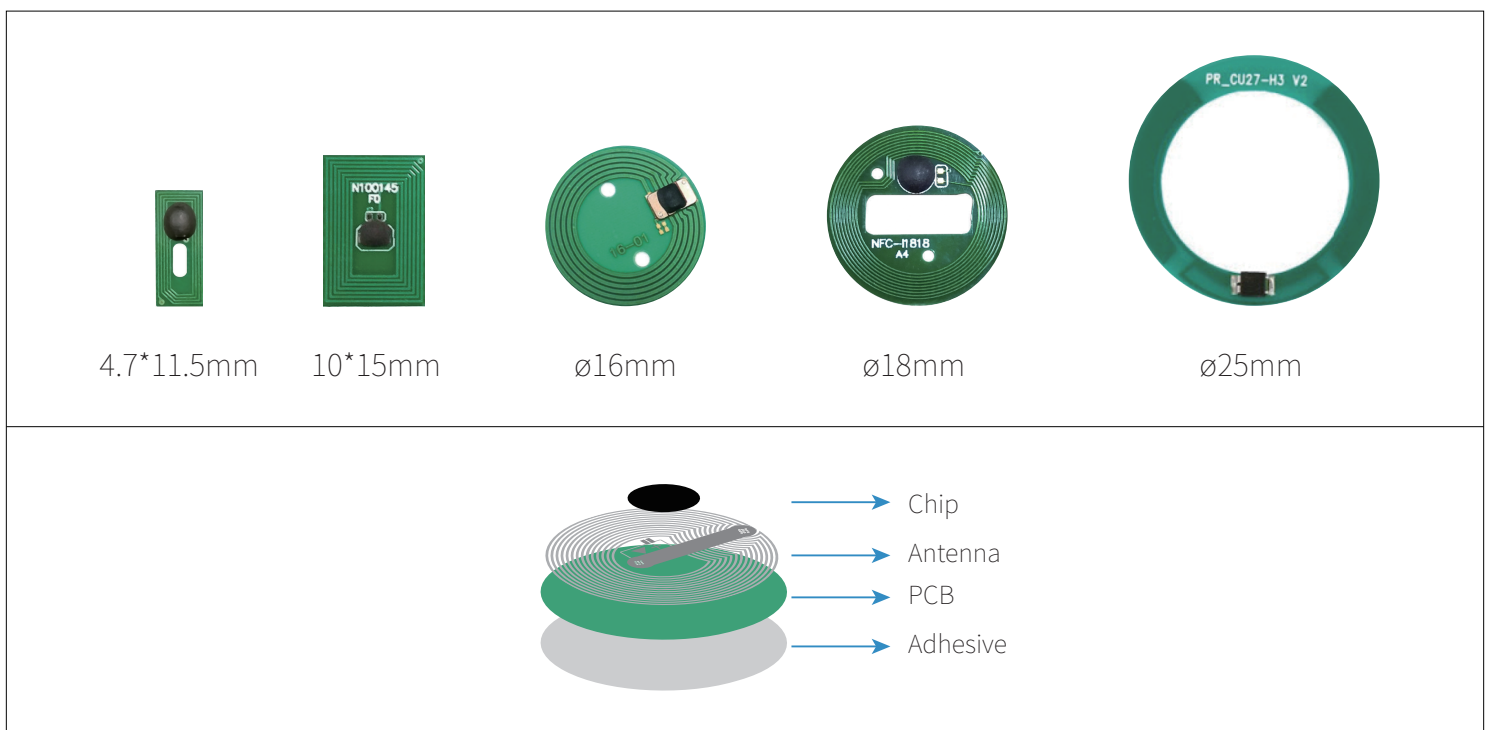
PCB NTAG 213 NFC Tag has the characteristics of high-temperature resistance, pressure resistance, and small size, etc. In the process of injection molding, due to its high-temperature resistance, the NFC chip will not be damaged by the Injection temperature, so it is ideal for integration into a variety of electronic devices, for Bluetooth pairing and information interaction with mobile phones.

Additionally, compared with NTAG 203 chip, NTAG 213 chip has a better RF performance and higher safety performance to prevent the tag from being dismantled or counterfeited. You can give each product with a PCB NTAG213 NFC tag to effectively prevent fake products from impacting the market.

### Parameters

Chip	NTAG 213	Material	PCB	Color	customized
Frequency	13.56KHz	Thickness	0.08mm-3.0mm	Protocol	ISO14443A
Write Endurance	100000 times	Temperature	-30°C to + 250°C	Operating Distance	up to 100 mm
Size	Ø 10mm,Ø 17mm,Ø 20mm,Ø 25mm,16*16mm,18*18mm18*25mm,12*18mm,12*18mm,10*25mm,12*22mm,etc.				

### Dimensional Diagram



### Feature

- ▶ UID ASCII mirror for automatic serialization of NDEF messages
- ▶ Automatic NFC counter triggered at read command
- ▶ NFC counter ASCII mirror for automatic adding the NFC counter value to the NDEF message
- ▶ Fast read command
- ▶ True anticollision

## Available chips

### HF 13.56 MHz Chips

Chip Name	Protocol	Capacity	Frequency
Ntag213	ISO14443A	180 byte	13.56 MHz
Ntag215	ISO14443A	540 byte	13.56 MHz
Ntag216	ISO14443A	924 byte	13.56 MHz
MIFARE Classic 1K	ISO14443A	1 KB	13.56 MHz
MIFARE Classic 4K	ISO14443A	4 KB	13.56 MHz
MIFARE Ultralight EV1	ISO14443A	80 byte	13.56 MHz
MIFARE Ultralight C	ISO14443A	192 byte	13.56 MHz
ICODE SLIX	ISO15693	1024 bits	13.56 MHz

## APPLICATIONS

- Applications with clear requirements for circuit stability, abrasion and corrosion resistance, such as pipeline production data inventory management under the high-temperature environment, inventory control of incoming and outgoing items, and inventory control of injection-molded plastic parts.
- Applications where modules need to be assembled or repackaged, such as Bluetooth speaker, Bluetooth headset or used to encapsulate special purpose labels like laundry labels, silicone wristbands, etc.